

Description

JMT N-channel Enhancement Mode Power MOSFET

Features

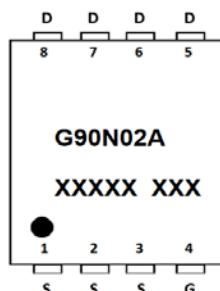
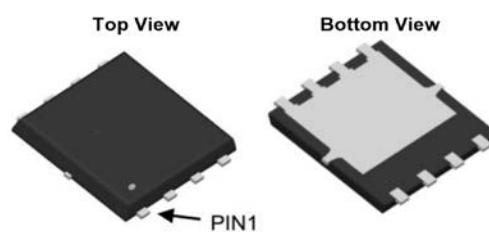
- 20V, 75A
 $R_{DS(ON)} < 3.6\text{m}\Omega @ V_{GS} = 4.5\text{V}$
 $R_{DS(ON)} < 4.7\text{m}\Omega @ V_{GS} = 2.5\text{V}$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free

Applications

- Load Switch
- PWM Application
- Power Management

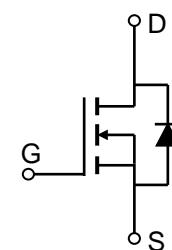


100% UIS TESTED!
100% ΔV_{ds} TESTED!



PDFN5x6-8L

Marking and Pin Assignment



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Outline	Package	Reel Size	Reel(pcs)	Per Carton (pcs)
G90N02A	JMTG90N02A	TAPING	PDFN5x6-8L	13"	5000	50000

Absolute Maximum Ratings (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Value		Units
V_{DS}	Drain-to-Source Voltage		20		V
V_{GS}	Gate-to-Source Voltage		± 12		V
I_D	Continuous Drain Current	$T_C = 25^\circ\text{C}$	75		A
		$T_C = 100^\circ\text{C}$	48		
I_{DM}	Pulsed Drain Current ⁽¹⁾		300		A
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾		156		mJ
P_D	Power Dissipation	$T_C = 25^\circ\text{C}$	40		W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽³⁾		33		$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance, Junction to Case		3.1		
T_J, T_{STG}	Junction & Storage Temperature Range		-55 to 150		$^\circ\text{C}$

**Electrical Characteristics** ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 20\text{V}, V_{GS} = 0\text{V}$	-	-	1.0	μA
I_{GSS}	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 12\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	0.5	0.8	1.0	V
$R_{\text{DS}(\text{ON})}$	Static Drain-Source ON-Resistance ⁽⁴⁾	$V_{GS} = 4.5\text{V}, I_D = 30\text{A}$	-	2.8	3.6	$\text{m}\Omega$
		$V_{GS} = 2.5\text{V}, I_D = 20\text{A}$	-	3.6	4.7	$\text{m}\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 10\text{V}, f = 1\text{MHz}$	-	3476	-	pF
C_{oss}	Output Capacitance		-	528	-	pF
C_{rss}	Reverse Transfer Capacitance		-	464	-	pF
Q_g	Total Gate Charge	$V_{GS} = 0 \text{ to } 8\text{V}$ $V_{DS} = 10\text{V}, I_D = 30\text{A}$	-	65	-	nC
Q_{gs}	Gate Source Charge		-	8	-	nC
Q_{gd}	Gate Drain("Miller") Charge		-	12	-	nC
Switching Characteristics						
$t_{d(\text{on})}$	Turn-On Delay Time	$V_{GS} = 10\text{V}, V_{DD} = 10\text{V}$ $I_D = 30\text{A}, R_{\text{GEN}} = 3\Omega$	-	8	-	ns
t_r	Turn-On Rise Time		-	19	-	ns
$t_{d(\text{off})}$	Turn-Off Delay Time		-	73	-	ns
t_f	Turn-Off Fall Time		-	80	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current	-	-	75	-	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	300	-	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = 30\text{A}$	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	$I_F = 20\text{A}, di/dt = 100\text{A/us}$	-	16	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	5.6	-	nC

Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

2. E_{AS} condition: Starting $T_J = 25^\circ\text{C}$, $V_{DD} = 10\text{V}$, $V_G = 10\text{V}$, $R_G = 25\text{ohm}$, $L = 0.5\text{mH}$, $I_{AS} = 25\text{A}$ 3. $R_{\theta JA}$ is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB4. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Typical Performance Characteristics

Figure 1: Output Characteristics

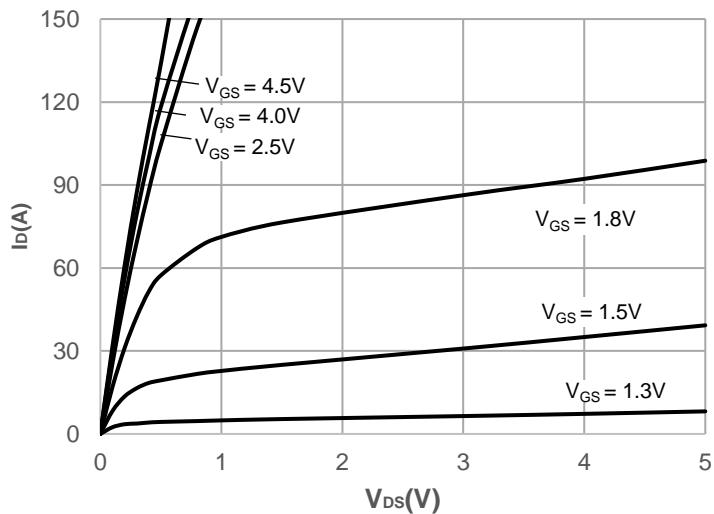


Figure 2: Typical Transfer Characteristics

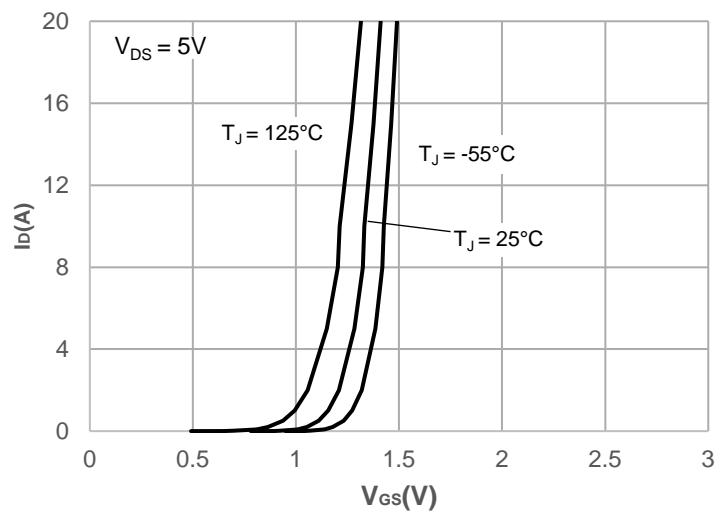


Figure 3: On-resistance vs. Drain Current

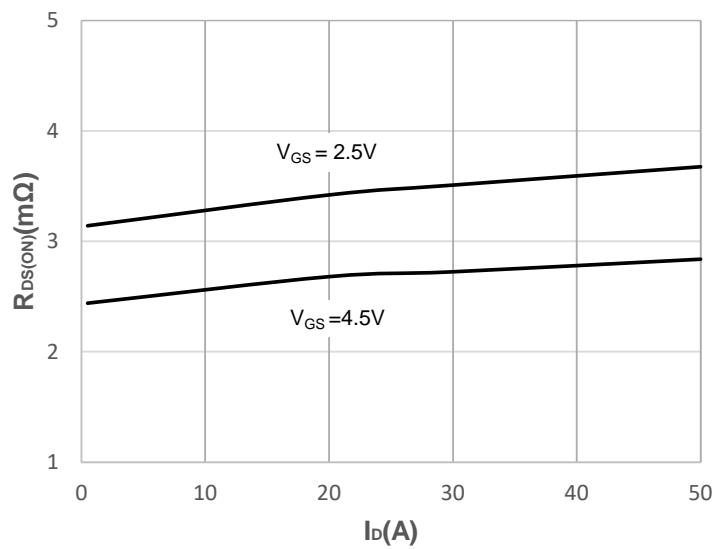


Figure 4: Body Diode Characteristics

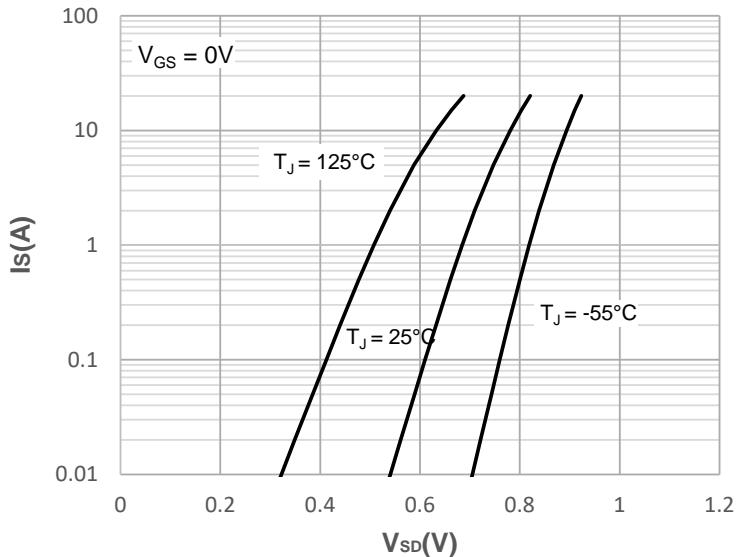


Figure 5: Gate Charge Characteristics

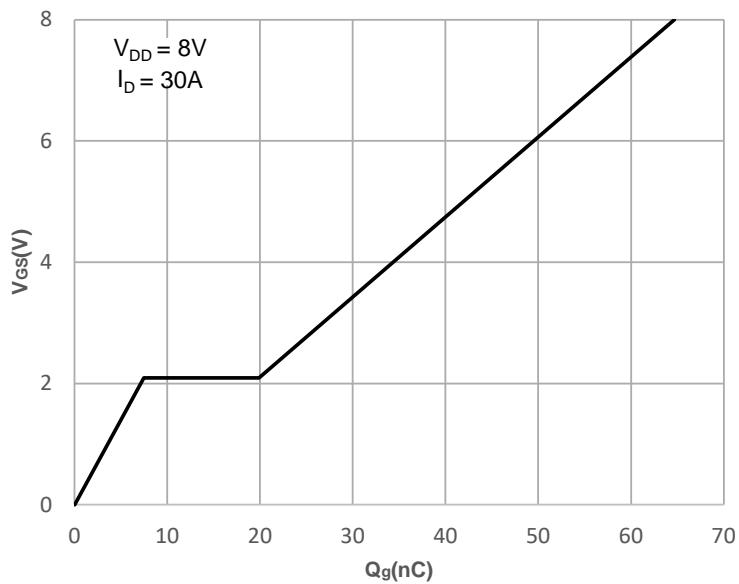
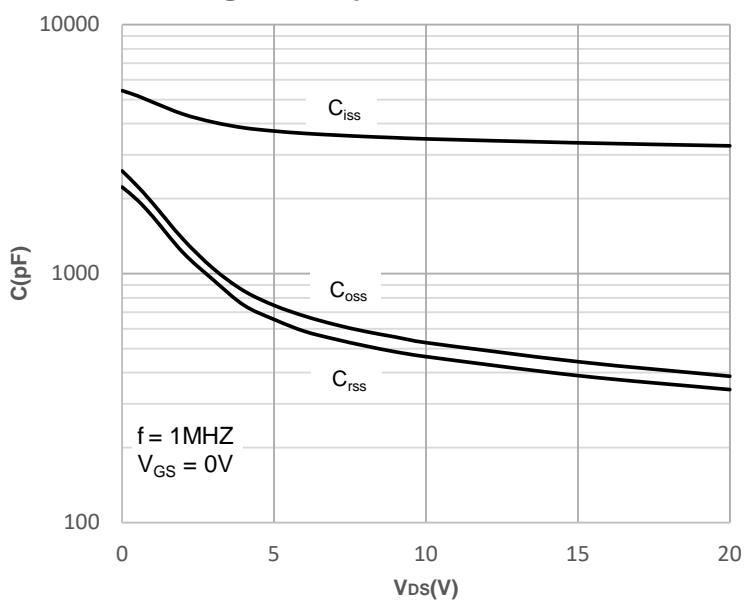


Figure 6: Capacitance Characteristics



Typical Performance Characteristics

Figure 7: Normalized Breakdown voltage vs. Junction Temperature

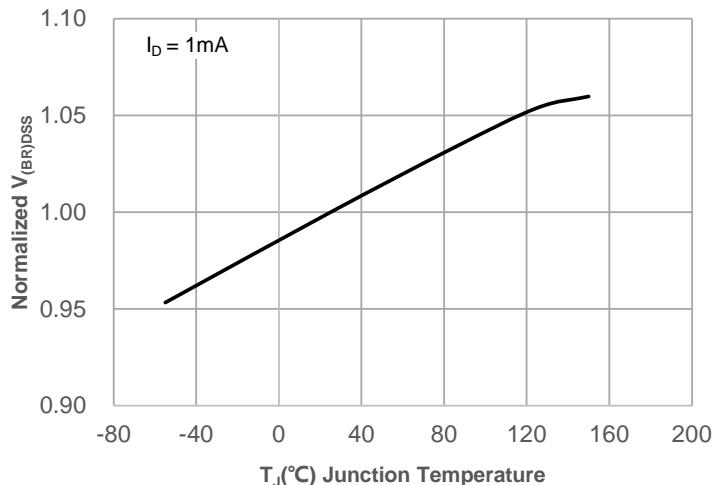


Figure 8: Normalized on Resistance vs. Junction Temperature

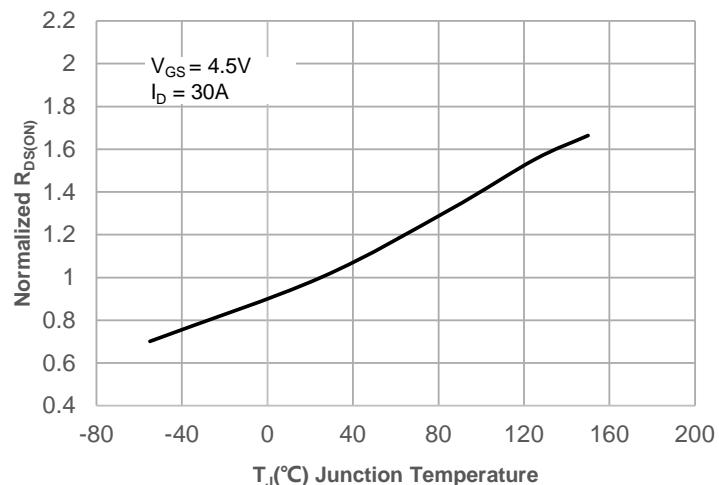


Figure 9: Maximum Safe Operating Area

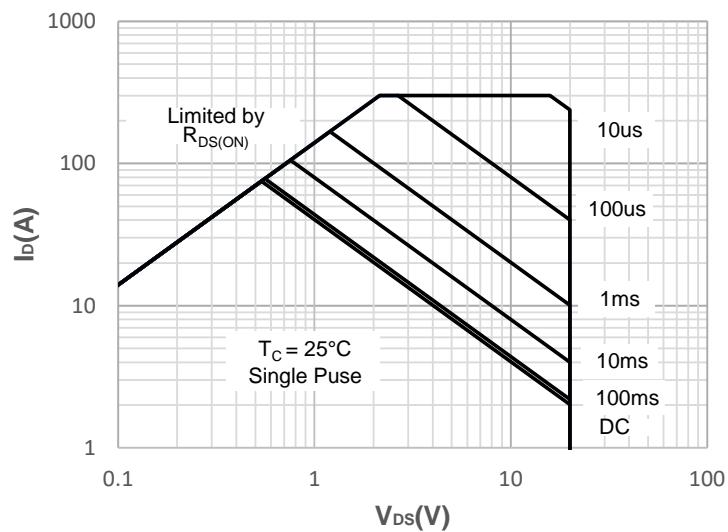


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

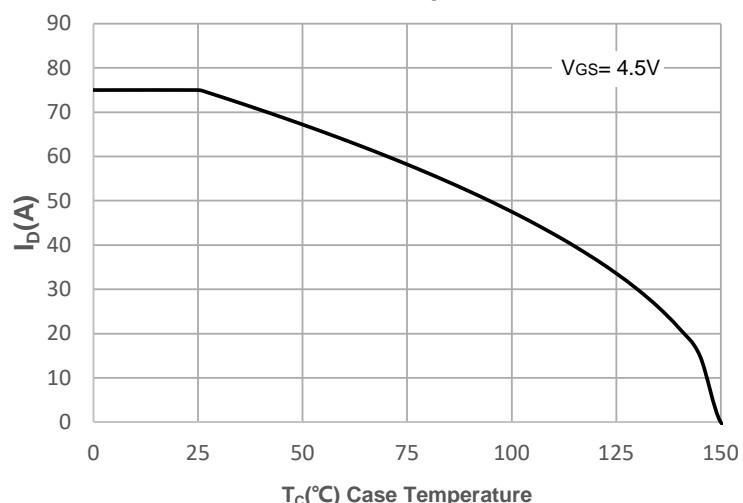


Figure 11: Normalized Maximum Transient Thermal Impedance

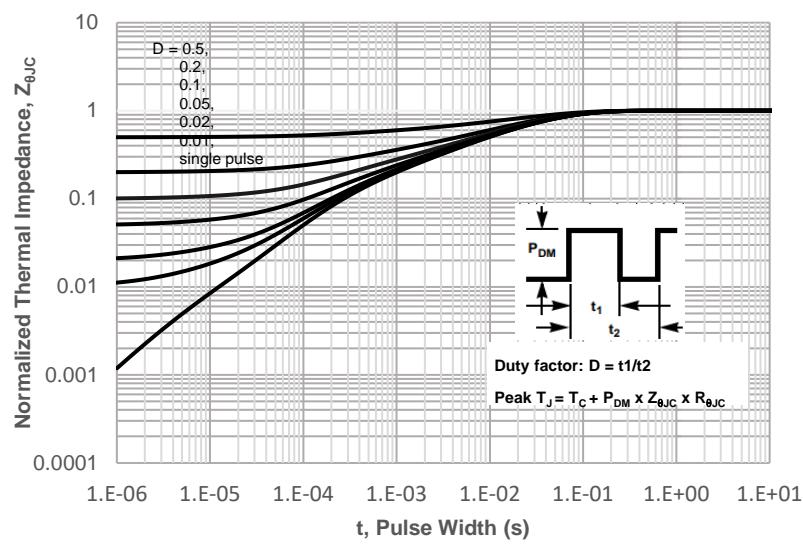
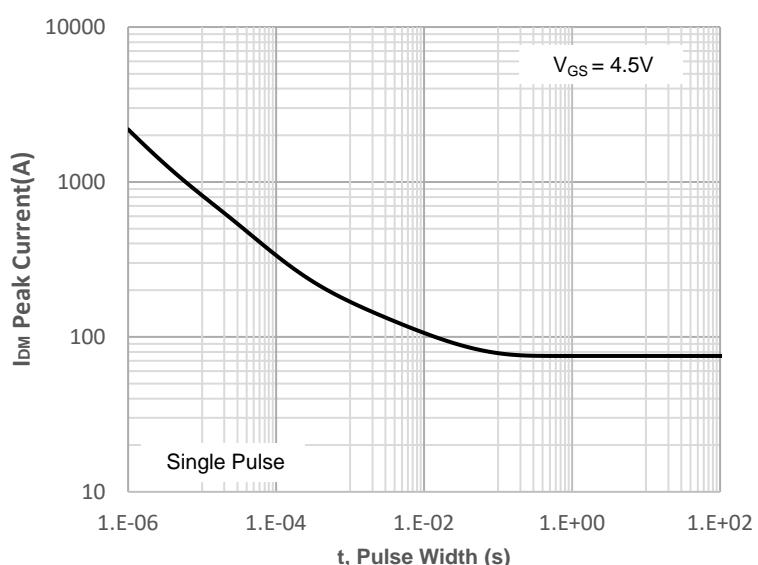


Figure 12: Peak Current Capacity



Test Circuit

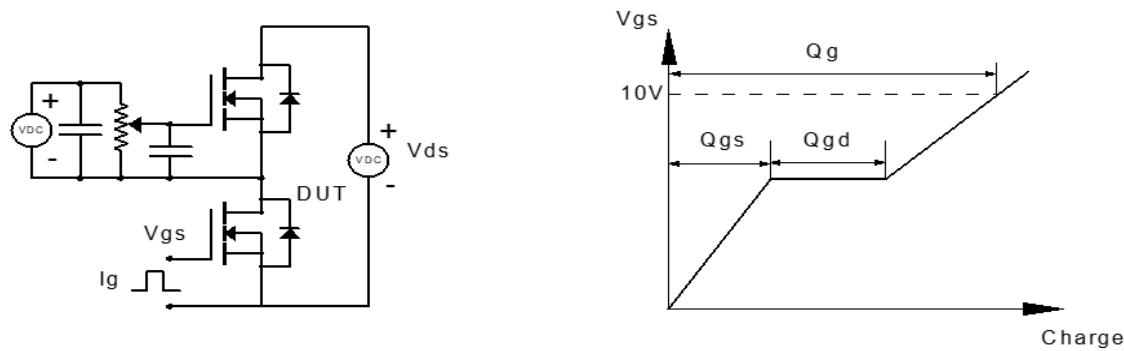


Figure 1: Gate Charge Test Circuit & Waveform

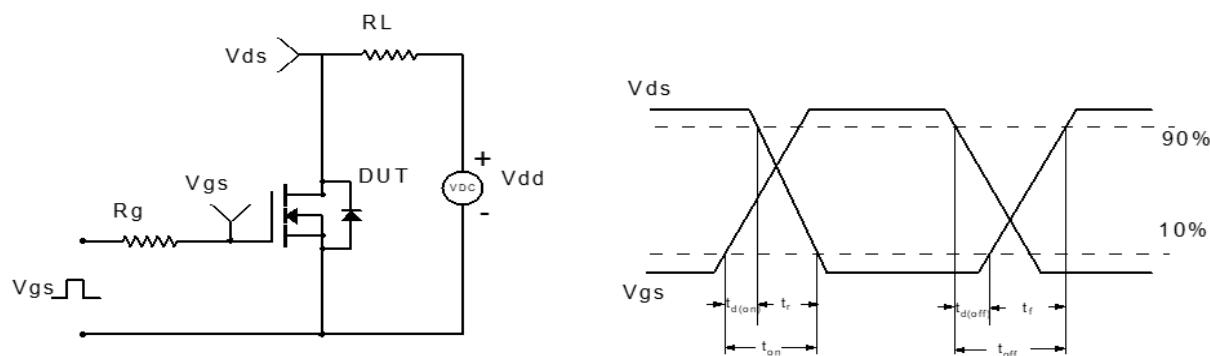


Figure 2: Resistive Switching Test Circuit & Waveform

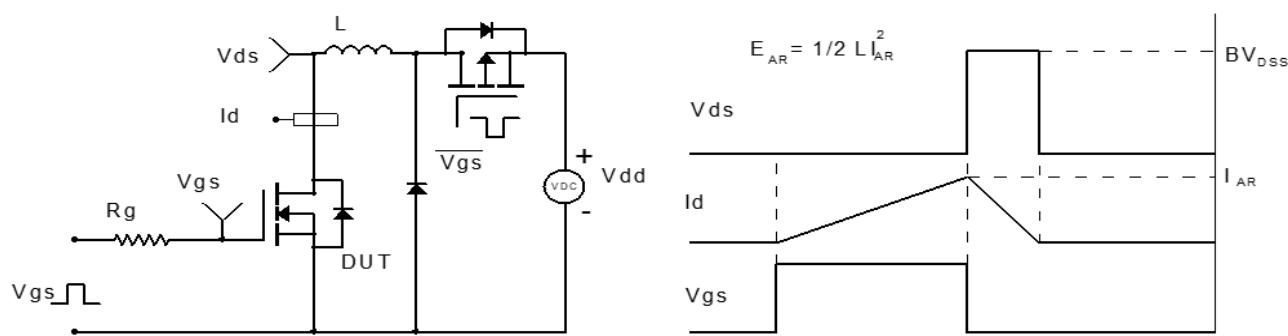


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

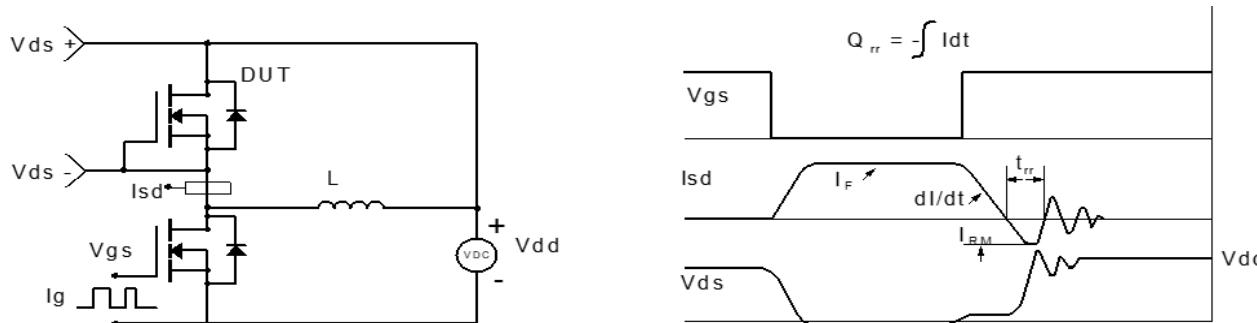
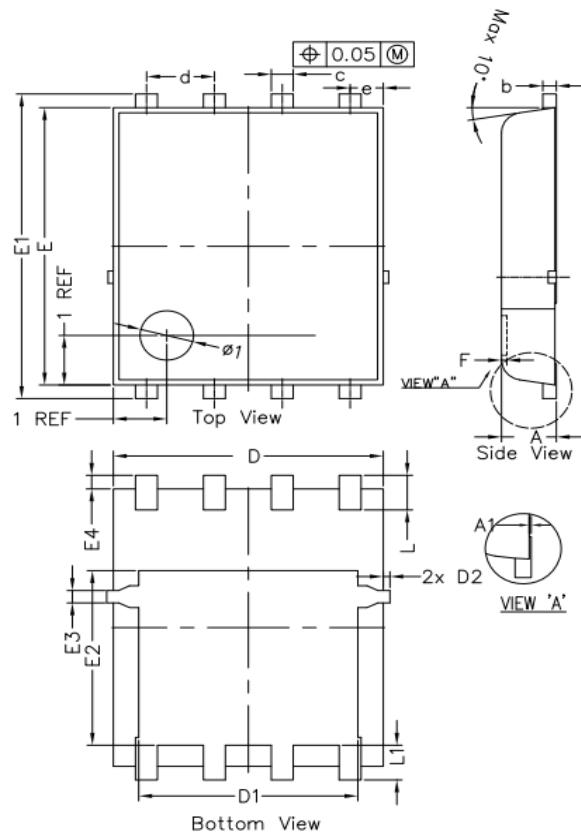


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(PDFN5x6-8L)



SYMBOLS	DIMENSION IN MM			DIMENSION IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
* A	0.900	1.000	1.100	0.035	0.039	0.043
A1	0.000	---	0.050	0.000	----	0.002
b	0.246	0.254	0.312	0.010	0.010	0.012
* c	0.310	0.410	0.510	0.012	0.016	0.020
d	1.27 BSC			0.050 BSC		
* D	4.950	5.050	5.150	0.195	0.199	0.203
D1	4.000	4.100	4.200	0.157	0.161	0.165
* D2	---	---	0.125	---	---	0.005
e	0.62 BSC			0.024 BSC		
* E	5.500	5.600	5.700	0.217	0.220	0.224
* E1	6.050	6.150	6.250	0.238	0.242	0.246
E2	3.425	3.525	3.625	0.135	0.139	0.143
E3	0.150	0.250	0.350	0.006	0.010	0.014
* E4	0.175	0.275	0.375	0.007	0.011	0.015
F	-	-	0.100	-	-	0.004
* L	0.500	0.600	0.700	0.02	0.02	0.03
L1	0.600	0.700	0.800	0.02	0.03	0.03

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